

S/N 10/722,838

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Suan J. Boon

Examiner: James Mitchell

Serial No.: 10/722,838

Group Art Unit: 2813

Filed: November 26, 2003

Docket: 303.601US3

Confirmation No.: 8165

Title: METHOD OF PACKAGING AT A WAFER LEVEL USING AN ADHESIVE
(as amended)

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

MS Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

In compliance with the duty imposed by 37 C.F.R. § 1.56, and in accordance with 37 C.F.R. §§ 1.97 *et. seq.*, the enclosed materials are brought to the attention of the Examiner for consideration in connection with the above-identified patent application. Applicants respectfully request that this Information Disclosure Statement be entered and the documents listed on the attached Form 1449 be considered by the Examiner and made of record. Pursuant to the provisions of MPEP 609, Applicants request that a copy of the 1449 form, initialed as being considered by the Examiner, be returned to the Applicants with the next official communication.

Pursuant to 37 C.F.R. §1.97(c)(2), Applicants hereby authorize the Commissioner to charge the fee of \$180.00 as set forth in 37 C.F.R. §1.17(p), to Deposit Account No. 19-0743. Please charge any additional fees or credit any overpayment to Deposit Account No. 19-0743.

Applicant brings to the attention of the Examiner the following Office Actions and responses associated with one or both of the inventors of the instant application and/or the assignee of the instant application. This material is available and accessible at the United States Patent and Trademark Office.

ELECTRONIC APPARATUS HAVING AN ADHESIVE LAYER FROM WAFER LEVEL PACKAGING

Application Serial No. 10/723,474 (Atty Ref 303.601US2) Response filed 04/14/08 to Non-Final Office Action mailed 12/13/07, 11 pgs
Application Serial No. 10/723,474 (Atty Ref 303.601US2) Final Office Action mailed 08/06/08, 11 pgs

METHOD OF PACKAGING AT A WAFER LEVEL USING AN ADHESIVE (as amended)

Application Serial No. 10/722,838 (Atty. Ref. 303.601US3), Restriction Requirement, 4 pgs

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WAFER LEVEL PRE-PACKAGED FLIP CHIP

Application Serial No. 11/460,089 (Atty Ref 303.601US4) Restriction Requirement mailed 5-30-08, 6 pgs

Application Serial No. 11/460,089 (Atty Ref 303.601US4) Response filed 6-30-08 to Restriction Requirement mailed 5-30-08, 12 pgs

WAFER LEVEL PRE-PACKAGED FLIP CHIP

Application Serial No. 11/460,093 (Atty Ref 303.601US5) Response filed 05/02/08 to Non-Final Office Action mailed 01/02/08, 11 pgs

Application Serial No. 11/460,093 (Atty. Ref. 303.601US5) Final Office Action mailed 07-31-08, 7 pgs

Application Serial No. 11/460,093 (Atty Ref 303.601US5) Response filed 9/15/2008 to Final Office Action mailed 7/31/2008, 7 pages

WAFER LEVEL PRE-PACKAGED FLIP CHIP SYSTEMS

Application Serial No. 11/460,435 (Atty Ref 303.601US6), Restriction Requirement mailed 1-24-08, 5 pgs

Application Serial No. 11/460,435 (Atty Ref 303.601US6) Response filed 2-25-08 to Restriction Requirement mailed 1-24-08, 9 pgs

Application Serial No. 11/460,435 (Atty Ref 303.601US6) Non Final Office Action Mailed 05-14-2008, 11 pgs

Application Serial No. 11/460,435 (Atty Ref 303.601US6) Response filed 9/15/2008 to Non-Final Office Action mailed 5/14/2008, 12 pgs

WAFER LEVEL PRE-PACKAGED FLIP CHIP SYSTEM

Application Serial No. 11/460,445 (Atty Ref 303.601US7), Restriction Requirement mailed 5-1-08, 5 pgs

Application Serial No. 11/460,445 (Atty Ref 303.601US7), Response filed 6-2-08 to Restriction Requirement mailed 5-1-08, 9 pgs

Application Serial No. 11/460,445 (Atty Ref 303.601US7), Non-Final Office Action mailed 09-05-08, 18 pgs

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Serial Number: 10/722,838

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Pursuant to 37 C.F.R. 1.98(a)(2), Applicant believes that copies of cited U.S. Patents and Published Applications, and Non-Published Applications identifiable by USPTO Serial Number, are no longer required to be provided to the Office. Notification of this change to this effect was provided in the United States Patent and Trademark Office OG Notice dated October 19, 2004. Thus, Applicant has not included copies of any US Patents or US Patent Applications identifiable by serial number that may be cited with this submission. Should the Office require copies to be provided, Applicant respectfully requests that notice of such requirement be directed to Applicant's below-signed representative. Applicant acknowledges the requirement to submit copies of foreign patent documents and non-patent literature in accordance with 37 C.F.R. 1.98(a)(2).

The Examiner is invited to contact the Applicants' Representative at the below-listed telephone number if there are any questions regarding this communication.

Respectfully submitted,

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Date 29 September 2008 By David R. Cochran
David R. Cochran
Reg. No. 46,632

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being filed using the USPTO's electronic filing system EFS-Web, and is addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on this 29th day of September, 2008.

Name Amy Moriarty

Signature [Signature]